

N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

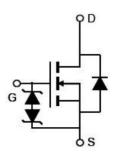
Features

- Optimized body diode reverse recovery performance
- Low on-resistance and low conduction losses
- ●Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application	n
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- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V _{DS min@Tjmax}	710	V
R _{DS(ON)TYP}	230	mΩ
ID	14.5	Α
Qg	22	nC



Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65N260D	TO-263-2L	NCE65N260D



TO-263

Table 1. Absolute Maximum Ratings (T_c=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	V _{DS}	650	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	14.5	Α
Continuous Drain Current at Tc=100°C	I _{D (DC)}	10.15	Α
Pulsed drain current (Note 1)	I _{DM (pluse)}	43.5	Α
Maximum Power Dissipation(Tc=25°C)	P _D	142	W
Derate above 25°C		0.94	W/°C
Avalanche current ^(Note 2)	I _{AS}	3.5	Α
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55+175	°C

^{*} limited by maximum junction temperature



Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	1.05	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

 Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	650			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±200	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	3	3.5	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =7A		230	260	mΩ
Dynamic Characteristics						
Input Capacitance	C _{lss}	\/ -50\/\/ -0\/		1104		pF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V,		40		pF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz		3		pF
Total Gate Charge	Qg			22		nC
Gate-Source Charge	Qgs	V _{DS} =480V,I _D =7A,		7		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V		5.5		nC
Gate plateau voltage	Vgp			5.5		V
Intrinsic gate resistance	Rg	f = 1 MHz open drain		18		Ω
Switching times			•			
Turn-on Delay Time	t _{d(on)}			11		nS
Turn-on Rise Time	t _r	V _{DD} =480V,I _D =7A,		9		nS
Turn-Off Delay Time	t _{d(off)}	$R_G=1.7\Omega, V_{GS}=10V$		57		nS
Turn-Off Fall Time	t _f			10		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T 0500			14.5	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			43.5	Α
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =14.5A,V _{GS} =0V		0.9	1.2	V
Reverse Recovery Time	t _{rr}	T: 0500 L 74		240		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I _F =7A,		2.0		uC
Peak Reverse Recovery Current	I _{rrm}	di/dt=100A/μs		17		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V, RG=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

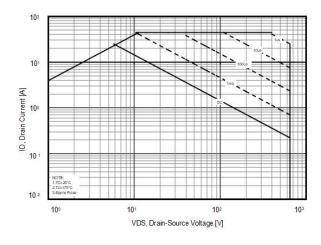


Figure 3. Transfer characteristics

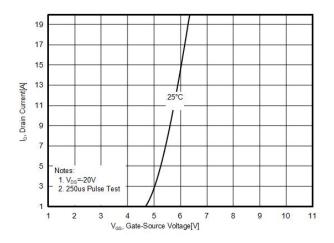


Figure 5. R_{DS(ON)} vs Junction Temperature

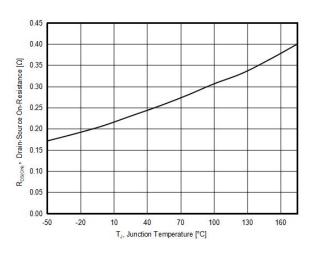


Figure 2. Capacitance

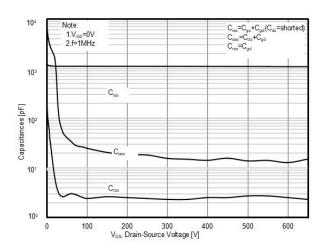


Figure 4. Output characteristics

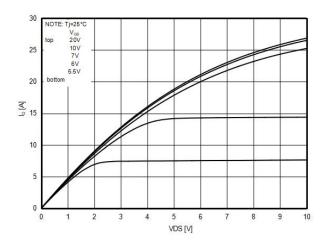


Figure 6. BV_{DSS} vs Junction Temperature

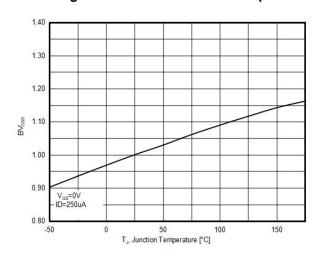




Figure 7. Maximum I_D vs Junction Temperature

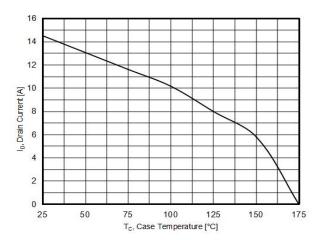


Figure 9. Static drain-source on resistance

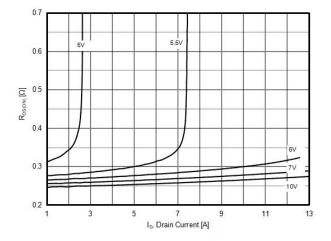


Figure 8. Gate charge waveforms

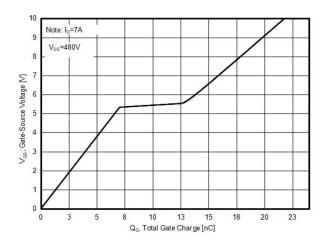
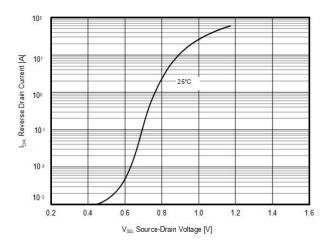


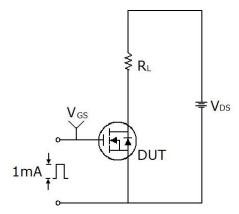
Figure 10. Source-Drain Diode Forward Voltag

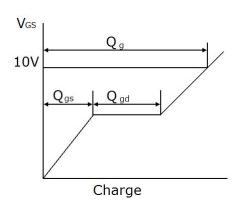




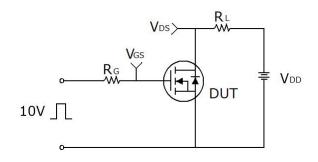
Test circuit

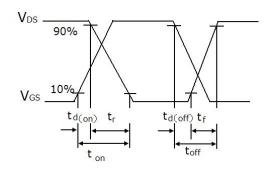
1) Gate charge test circuit & Waveform



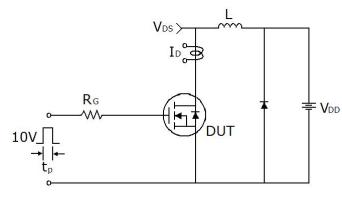


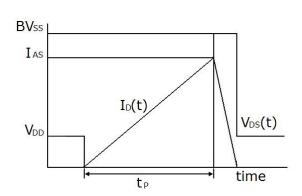
2) Switch Time Test Circuit:





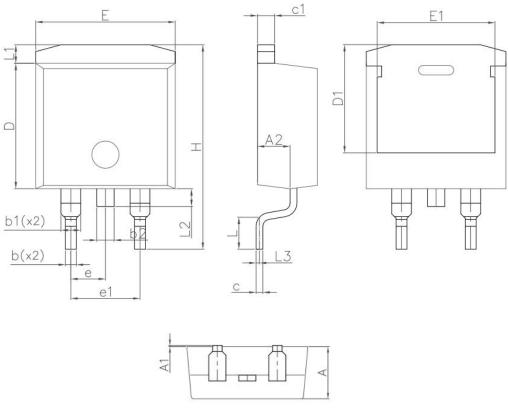
3) Unclamped Inductive Switching Test Circuit & Waveforms







TO-263-E Package Information



Symbol	Dimensions	Dimensions In Millimeters		s In Inches		
Зушьог	Min.	Max.	Min.	Max.		
Α	4.20	4.60	0.165	0.181		
A1	0.00	0.25	0.00	0.010		
A2	2.20	2.60	0.087	0.102		
b	0.70	0.90	0.028	0.035		
b1	1.20	1.75	0.047	0.069		
b2	1.17	1.37	0.046	0.054		
С	0.40	0.60	0.016	0.024		
c1	1.15	1.40	0.045	0.055		
D	9.10	9.30	0.358	0.366		
D1	7.63	8.23	0.300	0.324		
E	10.05	10.45	0.396	0.411		
E1	8.35	8.95	0.329	0.352		
е	2.54BSC		0.100BSC			
e1	5.08BSC		0.200)BSC		
Н	14.61	15.88	0.575	0.625		
L	1.78	2.79	0.070	0.110		
L1	1.3	1.36REF		0.054REF		
L2	1.3	1.30REF		IREF		



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